



3.3V CMOS 16-BIT BUS REGISTERED TRANSCEIVER, 5 VOLT TOLERANT I/O

IDT74LVC16652A

FEATURES:

- Typical $t_{sk(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to +85°C
- $V_{CC} = 3.3V \pm 0.3V$, Normal Range
- $V_{CC} = 2.7V$ to 3.6V, Extended Range
- CMOS power levels (0.4μW typ. static)
- All inputs, outputs and I/O are 5 Volt tolerant
- Supports hot insertion

Drive Features for LVC16652A:

- High Output Drivers: ±24mA
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

The LVC16652A 16-bit registered transceiver is built using advanced dual metal CMOS technology. This high-speed, low power device is organized as two independent 8-bit bus transceivers with 3-state D-type registers. For example, the OEAB and \overline{OEBA} signals control the transceiver functions.

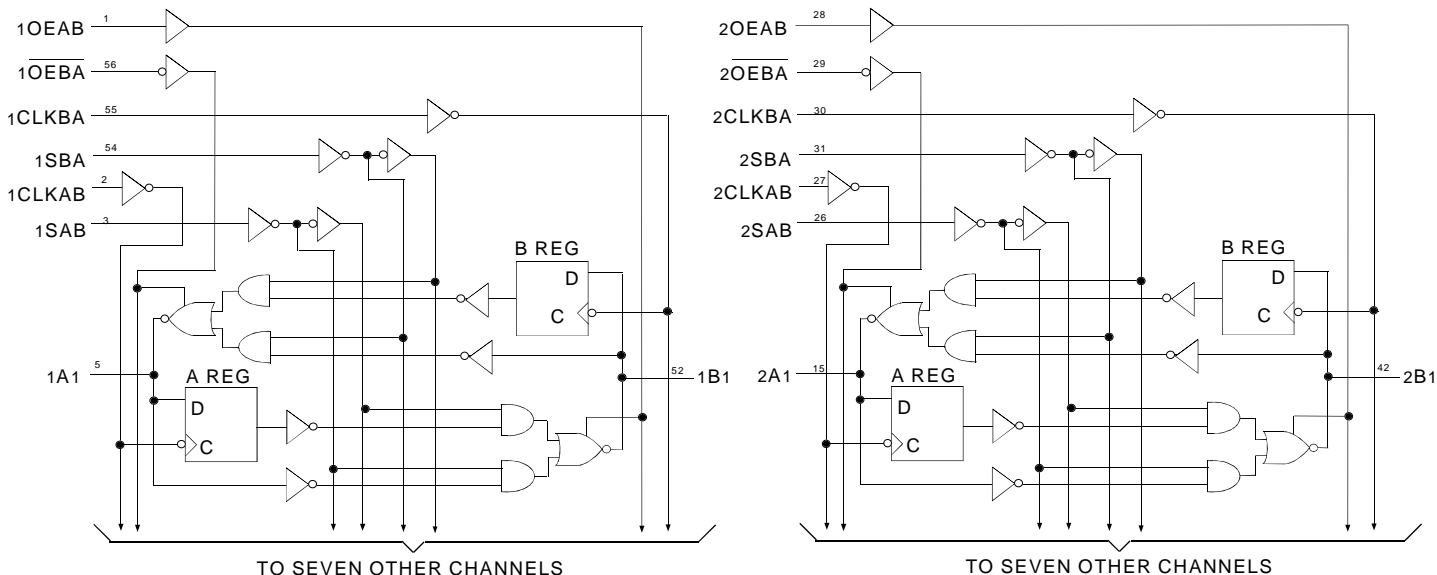
The SAB and the SBA control pins are provided to select either real time or stored data transfer. The circuitry used for select control will eliminate the typical decoding glitch that occurs in a multiplexer during the transition between stored and real time data. A Low input level selects real-time data and a High level selects stored data.

Data on the A or B data bus, or both, can be stored in the internal D-flip-flops by the Low-to-High transitions at the appropriate clock pins (CLKAB or CLKBA), regardless of the select or enable control pins. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

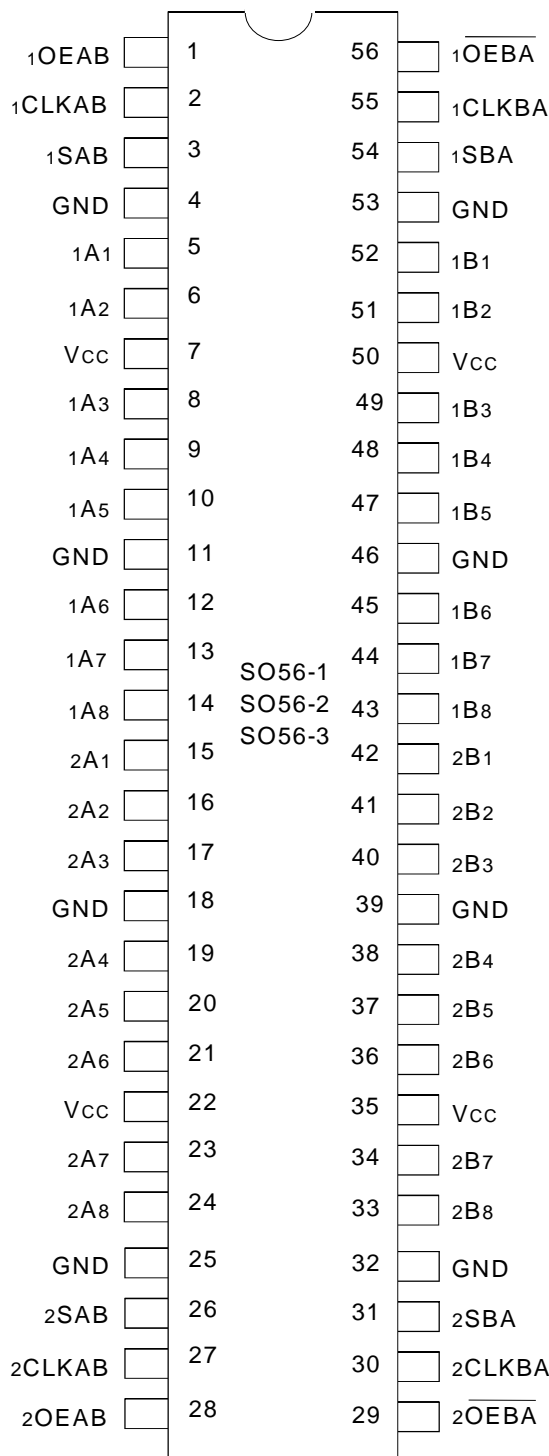
The LVC16652A is ideally suited for driving high capacitance loads and low-impedance backplanes.

All pins can be driven from either a 3.3V or 5V device. This feature allows the use of this device as a translator in a mixed 3.3V/5V supply system.

Functional Block Diagram



PIN CONFIGURATION



SSOP/ TSSOP/ TVSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS (1)

Symbol	Description	Max.	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	- 0.5 to +6.5	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	- 0.5 to +6.5	V
TSTG	Storage Temperature	- 65 to +150	°C
IOUT	DC Output Current	- 50 to +50	mA
IIK IOK	Continuous Clamp Current, VI < 0 or VO < 0	- 50	mA
ICC ISS	Continuous Current through each VCC or GND	±100	mA

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NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VCC terminals.
- All terminals except VCC.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	4.5	6	pF
COUT	Output Capacitance	VOUT = 0V	6.5	8	pF
CIO	I/O Port Capacitance	VIN = 0V	6.5	8	pF

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NOTE:

- As applicable to the device type.

PIN DESCRIPTION

Pin Names	Description
xAx	Data Register A Inputs Data Register B Outputs
xBx	Data Register B Inputs Data Register A Outputs
xCLKAB, xCLKBA	Clock Pulse Inputs
xSAB, xSBA	Output Data Source Select Inputs
xOEAB, xOEBA	Output Enable Inputs

FUNCTION TABLE (1, 2)

Inputs						Data I/O ⁽³⁾		Operation or Function
xOEAB	xOEBA	xCLKAB	xCLKBA	xSAB	xSBA	xAx	xBx	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X			Store A and B Data
X	H	↑	H or L	X	X	Input	Unspecified ⁽³⁾	Store A, Hold B
H	H	↑	↑	X ⁽²⁾	X	Input	Output	Store A in both Registers
L	X	H or L	↑	X	X	Unspecified ⁽³⁾	Input	Hold A, Store B
L	L	↑	↑	X	X ⁽²⁾	Output	Input	Store B in both Registers
L	L	X	X	X	L	Output	Input	Real Time B Data to A Bus
L	L	X	H or L	X	H			Stored B Data to A Bus
H	H	X	X	L	X	Input	Output	Real Time A Data to B Bus
H	H	H or L	X	H	X			Stored A Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Store A Data to B Bus and Stored B Data to A Bus

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
↑ = LOW-to-HIGH Transition
- Select Control = L: clocks can occur simultaneously.
Select Control = H: clocks can be staggered to load both registers.
- The data output functions may be enabled or disabled by various signals at the xOEAB or xOEBA inputs. Data input functions are always enabled, i.e. data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

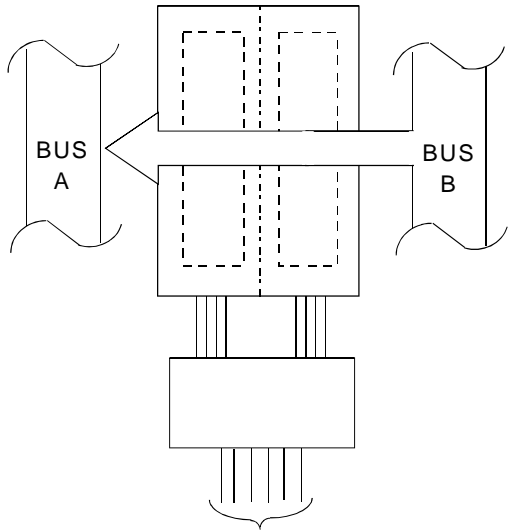
Operating Condition: TA = -40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
VIH	Input HIGH Voltage Level	VCC = 2.3V to 2.7V		1.7	—	—	V
		VCC = 2.7V to 3.6V		2	—	—	
VIL	Input LOW Voltage Level	VCC = 2.3V to 2.7V		—	—	0.7	V
		VCC = 2.7V to 3.6V		—	—	0.8	
IIH IIL	Input Leakage Current	VCC = 3.6V	VI = 0 to 5.5V	—	—	±5	µA
IOZH IOZL	High Impedance Output Current (3-State Output pins)	VCC = 3.6V	VO = 0 to 5.5V	—	—	±10	µA
IOFF	Input/Output Power Off Leakage	VCC = 0V, VIN or VO ≤ 5.5V		—	—	±50	µA
VIK	Clamp Diode Voltage	VCC = 2.3V, IIN = -18mA		—	-0.7	-1.2	V
VH	Input Hysteresis	VCC = 3.3V		—	100	—	mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	VCC = 3.6V	VIN = GND or VCC	—	—	10	µA
		3.6 ≤ VIN ≤ 5.5V ⁽²⁾		—	—	10	
ΔICC	Quiescent Power Supply Current Variation	One input at VCC - 0.6V other inputs at VCC or GND		—	—	500	µA

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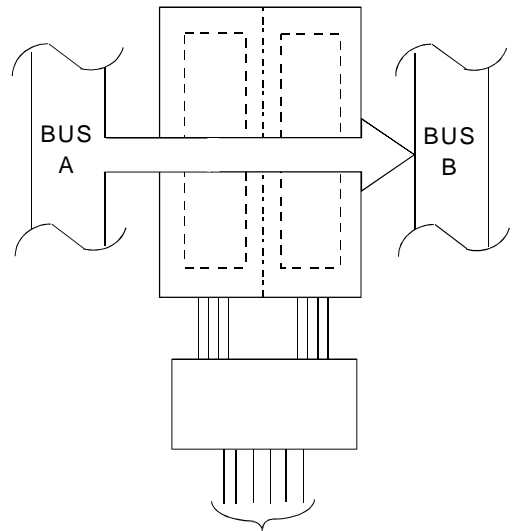
NOTES:

- Typical values are at VCC = 3.3V, +25°C ambient.
- This applies in the disabled state only.



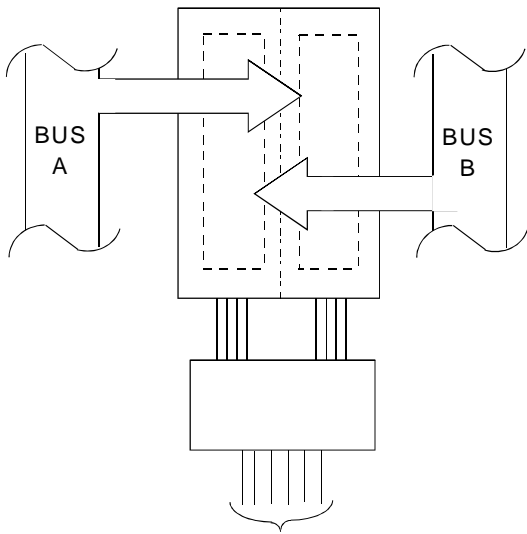
xOEAB	$\overline{\text{xOEBA}}$	xCLKAB	xCLKBA	xSAB	xSBA
L	L	X	X	X	L

**REAL-TIME TRANSFER
 BUS B TO A**



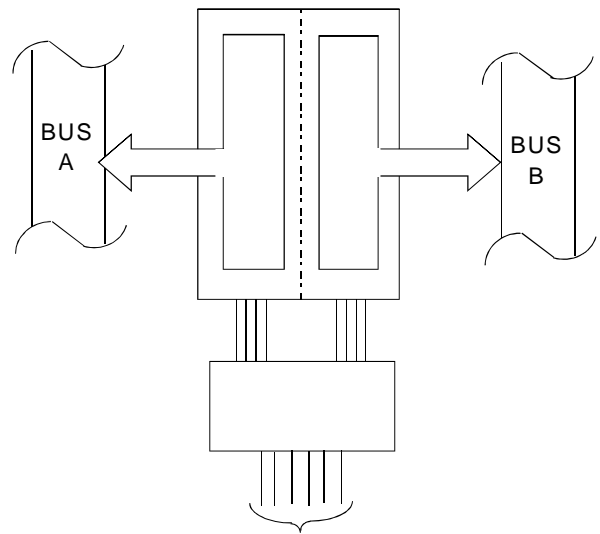
xOEAB	$\overline{\text{xOEBA}}$	xCLKAB	xCLKBA	xSAB	xSBA
H	H	X	X	L	X

**REAL-TIME TRANSFER
 BUS A TO B**



xOEAB	$\overline{\text{xOEBA}}$	xCLKAB	xCLKBA	xSAB	xSBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

**STORAGE FROM
 A, B, OR A AND B**



xOEAB	$\overline{\text{xOEBA}}$	xCLKAB	xCLKBA	xSAB	xSBA
H	L	H or L	H or L	H	H

**TRANSFER STORED
 DATA TO A AND/OR B**

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = 2.3V to 3.6V	I _{OH} = - 0.1mA	V _{CC} - 0.2	—	V
		V _{CC} = 2.3V	I _{OH} = - 6mA	2	—	
		V _{CC} = 2.3V	I _{OH} = - 12mA	1.7	—	
		V _{CC} = 2.7V		2.2	—	
		V _{CC} = 3.0V		2.4	—	
		V _{CC} = 3.0V	I _{OH} = - 24mA	2.2	—	
V _{OL}	Output LOW Voltage	V _{CC} = 2.3V to 3.6V	I _{OL} = 0.1mA	—	0.2	V
		V _{CC} = 2.3V	I _{OL} = 6mA	—	0.4	
			I _{OL} = 12mA	—	0.7	
		V _{CC} = 2.7V	I _{OL} = 12mA	—	0.4	
		V _{CC} = 3.0V	I _{OL} = 24mA	—	0.55	

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NOTE:

- V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. T_A = - 40°C to +85°C.

OPERATING CHARACTERISTICS, V_{CC} = 3.3V ± 0.3V, T_A = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per transceiver Outputs enabled	C _L = 0pF, f = 10Mhz	55	pF
CPD	Power Dissipation Capacitance per transceiver Outputs disabled		12	pF

SWITCHING CHARACTERISTICS (1)

Symbol	Parameter	V _{CC} = 2.7V		V _{CC} = 3.3V±0.3V		Unit
		Min.	Max.	Min.	Max.	
f _{MAX}		150	—	150	—	MHz
t _{PLH} t _{PHL}	Propagation Delay xAx to xBx or xBx to xAx	—	6.4	1.4	6.3	ns
t _{PLH} t _{PHL}	Propagation Delay xCLKAB or xCLKBA to xAx or xBx	—	7.3	2.4	6.4	ns
t _{PLH} t _{PHL}	Propagation Delay xSBA or xSAB to xAx or xBx	—	8.8	1.9	7.4	ns
t _{PZH} t _{PZL}	Output Enable Time xOEAB or xOEBA to xAx or xBx	—	6.6	1.6	6.3	ns
t _{PHZ} t _{PLZ}	Output Disable Time xOEAB or xOEBA to xAx or xBx	—	6.6	1.2	6.2	ns
t _{SU}	Set-up Time xAx or xBx HIGH or LOW Before xCLKAB↑ or xCLKBA↑	3.4	—	3	—	ns
t _H	Hold Time xAx or xBx HIGH or LOW After xCLKAB↑ or xCLKBA↑	0	—	0.2	—	ns
t _w	Clock Pulse Width HIGH or LOW	3.3	—	3.3	—	ns
t _{SK(0)}	Output Skew ⁽²⁾	—	—	—	500	ps

NOTES:

1. See test circuits and waveforms. T_A = - 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

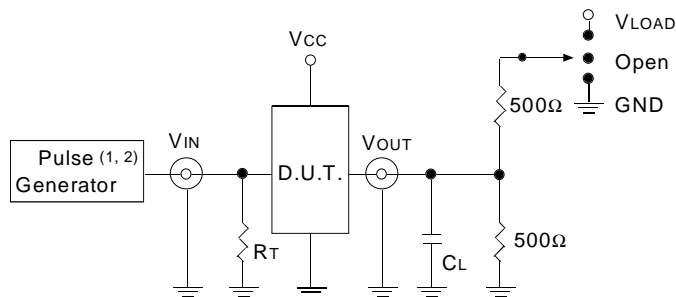
TEST CIRCUITS AND WAVEFORMS:

TEST CONDITIONS

Symbol	V _{CC} (1) = 3.3V ± 0.3V	V _{CC} (1) = 2.7V	V _{CC} (2) = 2.5V ± 0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

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TEST CIRCUITS FOR ALL OUTPUTS



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DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

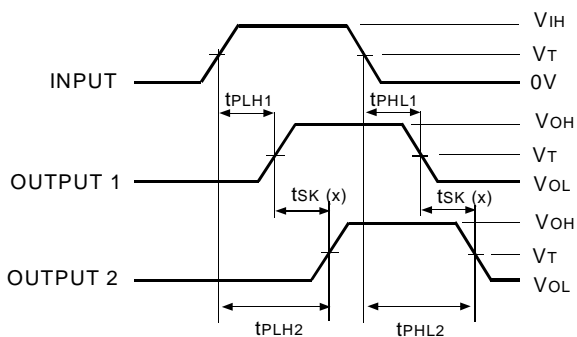
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

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OUTPUT SKEW - t_{SK}(x)



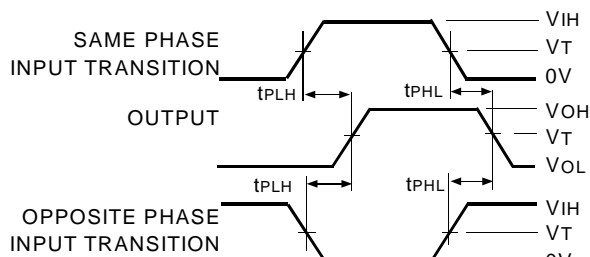
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

NOTES:

1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

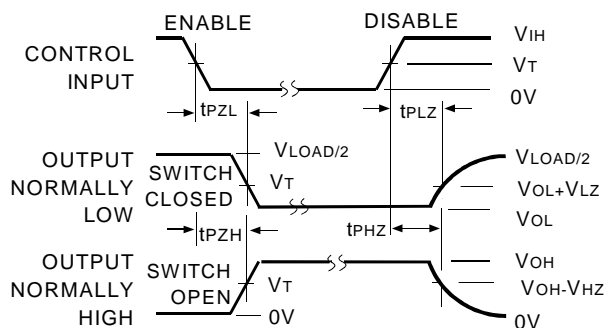
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PROPAGATION DELAY



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ENABLE AND DISABLE TIMES

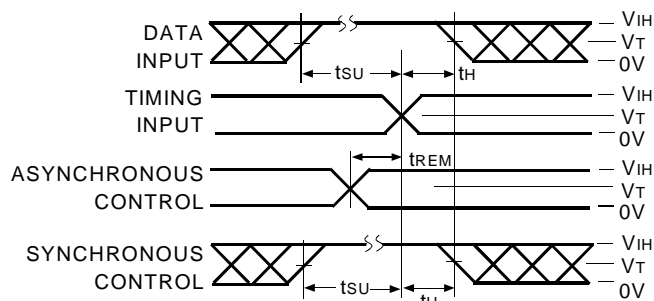


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NOTE:

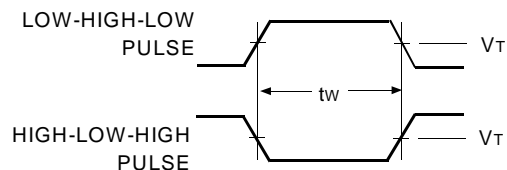
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



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PULSE WIDTH



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